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SEMICONDUCTOR DEVICE

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[There are no amendments to this patent.]

Abstract

Objective

To realize a small scale and a thinness of an appliance in which an infrared sensor element is housed.

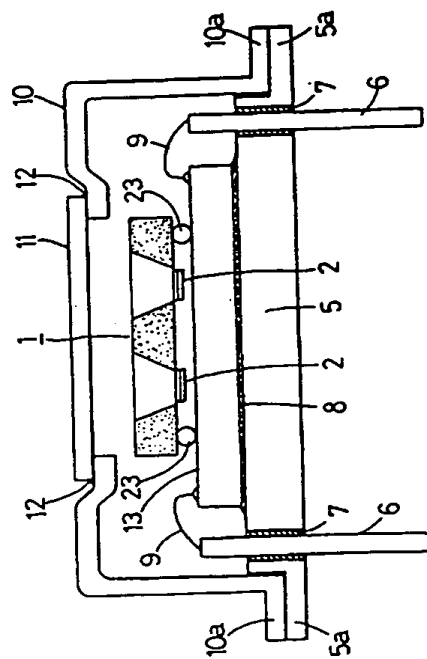
Constitution

A semiconductor device for mounting an infrared sensor element consists of an infrared sensor element 1, an LSI bare chip 13 for driving, which packs the semiconductor sensor element 1 on the upper surface via a protruded electrode 23, drives the above-mentioned semiconductor sensor element 1, and processes its output signal, a stem 5 for packing the LSI bare chip 13 for driving on the upper surface via a die bond paste, a terminal 6

that is penetrated and held in the stem 5 and connected to the above-mentioned LSI bare chip 13 for driving by a bonding wire 9, an approximately cylindrical cap 10 for protecting the inside in which the above-mentioned stem 5 is fixed at a lower opening, and a filter 11 fixed to an upper opening of the cap 10.

Effect

Since the infrared sensor element 1 and the LSI bare chip 13 for driving are integrated and housed in one package, the improvement of the printed-circuit board packing density as well as the small scale and thinness of an appliance are realized.



Claim

A semiconductor device characterized by the fact that in a semiconductor device for mounting an infrared sensor element, it includes a semiconductor sensor element 1, an LSI bare chip for driving, which packs the semiconductor sensor element on the upper surface via a protruded electrode, drives the above-mentioned semiconductor sensor element, and processes its output signal, a stem for packing the LSI bare chip for driving on the upper surface via a die bond paste, a terminal that is penetrated and held in the stem 5 and connected to the above-mentioned LSI bare chip for driving by a bonding wire, an approximately cylindrical cap for protecting the inside in which the above-mentioned stem is fixed at a lower opening, and a filter fixed to an upper opening of the cap.

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